

78. (New) The process of claim 77 further comprising depositing one or more additional dyad, each additional dyad comprising an additional conductive barrier material layer and a transparent layer selected from the group consisting of a layer of organic polymer, a layer of dielectric, a layer of metal and a layer of conductive oxide.

REMARKS

Claims 1-38 have been cancelled. New claims 39-78 have been added.

Support for the newly added claims may be found in the Second Substitute Specification. Specific details are listed in the Table below.

| New Claim | Original Claim | Support |
|-----------|----------------|---|
| 39-65 | | Original claims 1-38 |
| 66 | | p. 12, lines 10-15 |
| 67 | | p. 4 lines 11-16 |
| 68 | | p. 4, lines 2-3 and p.14, line 22-23 |
| 69 | | p. 9, lines 33-35 |
| 70 | | p. 13, lines 13-16 |
| 71 | | p. 13, lines 13-16 and lines 23-29 |
| 72 | | p. 4, lines 23-24 |
| 73 | | Figure 1 |
| 74 | | p. 5, lines 32-35 |
| 75 | | Figure 1 |
| 76 | | p. 9, lines 8-23 |
| 77 | | Figure 1 |
| 78 | | p. 5, lines 32-35 |

Examination and consideration of the application is requested.

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Respectfully submitted,

By

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